CALL FOR PAPERS

37TH INTERNATIONAL CONFERENCE ON CONSUMER ELECTRONICS 2019

ICCE 2019

CFP – DEADLINE: June 30, 2018

The IEEE Consumer Electronics (CE) Society is soliciting technical papers for oral and poster presentations at their 37th annual flagship conference, IEEE International Conference on Consumer Electronics (ICCE) in Las Vegas. ICCE is the established forum for innovative research in all areas of consumer electronics and is co-located with the CTA’s International Consumer Electronics Show (CES). CES is world’s largest consumer electronics trade-conference. The theme of ICCE 2019 is “Smart Electronics: Paradigms for Secure and Green Solutions”. Topics consistent with this theme include all aspects of foundation technologies and robust architectures that support privacy, reliability, anti-counterfeiting, authentication, content protection for consumer electronics devices, their networks, and the services connected to these devices.

Paper contributions are sought in but are not limited to following areas:

1. Security and Privacy of CE Hardware and Software Systems (SPC)
2. Energy Management of CE Hardware and Software Systems (EMC)
3. Application-Specific CE for Smart Cities (SMC)
4. RF, Wireless, and Network Technologies (WNT)
5. Internet of Things and Internet of Everywhere (IoT)
6. Entertainment, Gaming, and Virtual and Augmented Reality (EGV)
7. Audio, Music and Video Systems, and Cameras and Acquisition (AVS)
8. Automotive CE Applications (CEA)
9. CE Sensors and MEMS (CSM)
10. Consumer Healthcare Systems (CHS)
11. Enabling and HCI Technologies (HCI)
12. Smartphone and Mobile Device Technologies (MDT)

Authors are invited to submit original, unpublished manuscripts of 2- to 6-page length at https://edas.info/showConferenceDetails.php?c=23404. Previously published papers or papers under review for other conferences/journals should not be submitted for consideration. Authors may prepare original work of maximum 6 pages with a 200-word abstract using double-column IEEE conference-format template: http://www.ieee.org/conferences_events/conferences/publishing/templates.html.

All accepted papers (including regular papers, special session papers) will be published in the ICCE 2019 Digest or Proceedings and submitted to IEEE Xplore. Instructions for authors and document templates are available on the conference website. A selected set of papers from ICCE 2019 program will be invited for submission to special issues of peer-reviewed journals (e.g., IEEE CE Magazine) based on reviewer’s feedback and quality of conference presentation.

In addition to regular oral and poster sessions based on the above tracks, ICCE 2019 will have many special sessions on current hot topics related to CE. ICCE 2019 will also feature industry tracks as an integral part. The technical program committee invites proposals for

Important Dates of ICCE 2019 are the following:
Submission Deadline: June 30, 2018
Acceptance Notification: September 05, 2018
Submission of Final Version: September 25, 2018
Call for Special Session and Expert Panel Proposals:

The organizing committee invites proposals for Special Sessions and Expert Panels on the current hot topics in CE areas. These proposals can be submitted at the EDAS link. The deadline is same as the regular submissions deadline. The Special Session and Expert Panel Proposals should follow these guidelines:

1. Not exceed two pages.
2. Should describe the topic, the format and intended audience.
3. Must include the session title, the organizers, and a list of suggested participants with their biographical data and presentation topics. It is preferred to have three talks in each special session (maximum of three papers can be included in a session).
4. Sessions with two talks of 30 mins duration each as well as Sessions of 1hr tutorial/talk are also considered.
5. Submit online at EDAS choosing the following track:
   ST01: Special Session Proposals (SSP)
   ST02: Expert Panel Proposals (EPP)

The Special Sessions can be either oral presentations or poster presentations. Speaker presenting the work at the special session needs to register at the conference, and has the opportunity to include a paper up to 6 pages (minimally a 1-page extended abstract required) in the proceedings. Papers will be reviewed and published in the conference proceedings.

Call for Student Research Forum (SRF) Papers:

ICCE 2019 will feature a student research forum (SRF) as an integral part. The ICCE 2019 organizing committee invites perspective authors to submit their original unpublished work of maximum 4 pages using IEEE double-column conference format-template. Manuscripts in PDF format should be submitted to the “Student Research Forum” track at the online submission link at EDAS choosing the following track:

FT01: Student Research Forum (SRF).

The submission deadline is the same as specified for the regular paper submissions. All the accepted student research forum papers after reviewing will be published in the conference proceedings. The mode of presentation of Student Research Forum (SRF) papers is “poster”. The primary/first author of the SRF papers needs to be a student. Author presenting the work at the Student Research Forum (SRF) needs to register at the conference, and has the opportunity to include a paper up to 4 pages (minimally a 2-page extended abstract required) in the proceedings. Papers will be reviewed and published in the conference proceedings.

Important dates of ICCE 2019 are the following:

Submission Deadline: June 30, 2018
Acceptance Notification: September 05, 2018
Submission of Final Version: September 25, 2018

Special Session Tracks of ICCE 2019:

ST01: Machine learning, Deep learning and AI in Consumer Electronics
ST02: Smart Systems: Security-Power/Energy Tradeoff for Application Specific Processor Hardware
ST03: Blockchain Technology for Consumer Electronics Devices
ST04: Digital Experience in Consumer Electronics
ST05: AR/VR Display Technology
ST06: Human Interface Technologies for Automobile (AVA)
ST07: Hardware-based Security in Cyber Physical Systems
ST08: Deep Learning & Perception on Conventional and Emerging Platforms